

In the Claims

Please amend the claims as follows.

1. (Currently Amended) A method for manufacturing a printed circuit bonded to a heat sink using a two-step bonding process, comprising:
 - producing the printed circuit comprising at least one conductive layer circuit pattern laminated to at least one side of a dielectric layer;
 - in a first bonding step, first adhering a first side of a bond film to the printed circuit by partially activating an adhesive on the bond film such that the printed circuit is tack-bonded to the bond film, wherein the ~~first~~ adhering conforms the printed circuit to the bond film to substantially remove air entrapment between the printed circuit and the bond film; and
 - in a second bonding step, second adhering a second side of the bond film to the heat sink.
2. (Currently Amended) The method of claim 1, wherein the ~~first~~ adhering in the first bonding step is performed at a lower temperature than the ~~second~~ adhering in the second bonding step.
3. (Cancelled).
4. (Currently Amended) The method of claim 1, wherein the heat sink is primed with a primer coating of adhesive before the ~~second~~ adhering in the second bonding step.
5. (Original) The method of claim 4, wherein the primer coating has a thickness in a range of about 0.1 to about 2 microns.

6. (Currently Amended) The method of claim 1, wherein the ~~first~~ adhering in the first bonding step is performed with a platen press.
7. (Original) The method of claim 1, wherein the bond film is a thermoplastic resin film.
8. (Original) The method of claim 1, wherein the bond film is a composite film comprising two adhesive layers and a dielectric layer.
9. (Original) The method of claim 8, wherein the two adhesive layers on the bond film are made of different adhesive materials.
10. (Original) The method of claim 1, wherein the bond film includes ceramic powder filler.
11. (Original) The method of claim 1, wherein the printed circuit comprises a plurality of individual circuits.
12. (Currently Amended) The method of claim 11, further comprising ~~depanelizing~~ separating the plurality of individual circuits before the ~~second~~ adhering in the second bonding step.
13. (Withdrawn) A method for manufacturing a printed circuit bonded to a heat sink, comprising:
 - producing the printed circuit comprising at least one conductive layer circuit pattern laminated to at least one side of a dielectric layer;
 - stacking a plurality of circuit pre-assemblies, wherein each of the plurality of circuit pre-assemblies comprising a bond film, the printed circuit, conformance materials, and at least one release sheet;
 - first adhering the plurality of circuit pre-assemblies, wherein the first adhering adheres the bond film to the printed circuit in each of the plurality of

circuit pre-assemblies to produce a plurality of printed circuit-bond film assemblies; and

second adhering a heat sink to each of the printed circuit-bond film assemblies.

14. (Withdrawn) The method of claim 13, wherein the first adhering uses a platen press.
15. (Withdrawn) The method of claim 13, wherein the first adhering is performed at a lower temperature than the second adhering to the heat sink.
16. (Withdrawn) The method of claim 13, wherein the first adhering produces a tack bond between the printed circuit and the bond film.
17. (Withdrawn) The method of claim 13, wherein the heat sink is primed with a primer coating of adhesive before the second adhering.
18. (Withdrawn) The method of claim 17, wherein the primer coating has a thickness in a range of about 0.1 to about 2 microns.
19. (Withdrawn) The method of claim 13, wherein the first adhering uses at least one plate to press the plurality of elements.
20. (Withdrawn) The method of claim 13, wherein the bond film is a thermoplastic resin film.
21. (Withdrawn) The method of claim 13, wherein the bond film is a composite film comprising two adhesive layers and a dielectric layer.
22. (Withdrawn) The method of claim 21, wherein the two adhesive layers on the bond film are made of different adhesive materials.

23. (Withdrawn) The method of claim 12, wherein the bond film includes ceramic powder filler.

24. (Withdrawn) An apparatus, comprising:

- a printed circuit comprising at least one conductive layer circuit pattern laminated to at least one side of a dielectric layer;

- a heat sink; and

- a bond film, wherein the bond film laminates the heat sink to the printed circuit, and wherein the bond film is tack-bonded to the printed circuit prior to laminating to the heat sink.